



Technical Note

G5 300

Release date:

August 28th 2013

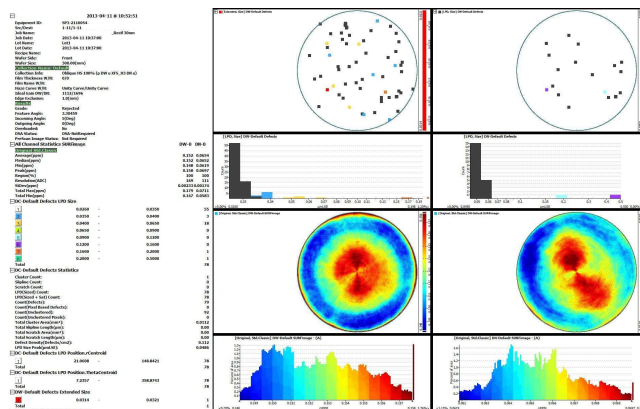
The **G5 300** wafer sorter is providing IC manufacturers with the highest productivity solution. Its motorization and cinematic enables a high throughput within a compact footprint.

Its end effectors embedding patented ACT, ensure unsurpassed cleanliness, as well as a safe wafer handling.

Our advanced design will support you at each step of your manufacturing improvement.

RECIF Technologies delivered in March 2013, multiple sets of G5 300 to a US based global leader in manufacturing solutions. After an "in depth particle characterization run", the conclusion was that the G5 300 platform was entirely fulfilling, and even exceeding expectations in term of particle cleanliness, and otherwise.

The G5 platform has been characterized on the newly released KLA Tencor Surfscan SP3. The results demonstrated its capability to handle wafers with a ultra high level of cleanliness, down to a 26 nm particle size; the smallest ever performed. See results here after:



Sample of RECIF G5 platform particle scan



	2013 Surfscan SP3		2007 Surfscan SP2	
	26 nm	40 nm	26 nm	40 nm
PWP results Particles per Wafer Pass – Front face Based on 1000 transfers test	0.0049	0.0034	NA	0.01

Conclusion :

Thanks to its outstanding cleanliness results achieved at 26 nm and 40 nm, the G5 platform demonstrated its continuous improvement over the years, and proved being the tool of choice to support the wafer manufacturing at the most advanced nodes, toward the 1x nm and beyond.

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